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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	AVR
Core Size	8-Bit
Speed	8MHz
Connectivity	SPI, UART/USART, USI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega645v-8ai

The fast-access Register File contains 32 x 8-bit general purpose working registers with a single clock cycle access time. This allows single-cycle Arithmetic Logic Unit (ALU) operation. In a typical ALU operation, two operands are output from the Register File, the operation is executed, and the result is stored back in the Register File – in one clock cycle.

Six of the 32 registers can be used as three 16-bit indirect address register pointers for Data Space addressing – enabling efficient address calculations. One of the these address pointers can also be used as an address pointer for look up tables in Flash program memory. These added function registers are the 16-bit X-, Y-, and Z-register, described later in this section.

The ALU supports arithmetic and logic operations between registers or between a constant and a register. Single register operations can also be executed in the ALU. After an arithmetic operation, the Status Register is updated to reflect information about the result of the operation.

Program flow is provided by conditional and unconditional jump and call instructions, able to directly address the whole address space. Most AVR instructions have a single 16-bit word format. Every program memory address contains a 16- or 32-bit instruction.

Program Flash memory space is divided in two sections, the Boot Program section and the Application Program section. Both sections have dedicated Lock bits for write and read/write protection. The SPM instruction that writes into the Application Flash memory section must reside in the Boot Program section.

During interrupts and subroutine calls, the return address Program Counter (PC) is stored on the Stack. The Stack is effectively allocated in the general data SRAM, and consequently the Stack size is only limited by the total SRAM size and the usage of the SRAM. All user programs must initialize the SP in the Reset routine (before subroutines or interrupts are executed). The Stack Pointer (SP) is read/write accessible in the I/O space. The data SRAM can easily be accessed through the five different addressing modes supported in the AVR architecture.

The memory spaces in the AVR architecture are all linear and regular memory maps.

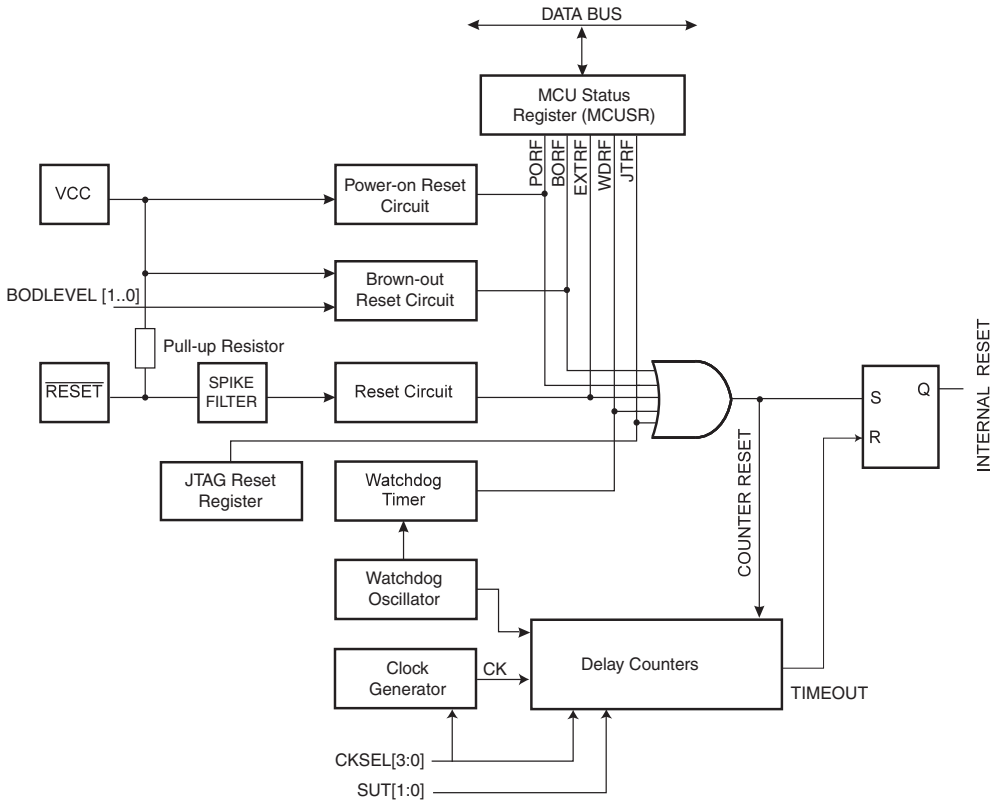
A flexible interrupt module has its control registers in the I/O space with an additional Global Interrupt Enable bit in the Status Register. All interrupts have a separate Interrupt Vector in the Interrupt Vector table. The interrupts have priority in accordance with their Interrupt Vector position. The lower the Interrupt Vector address, the higher the priority.

The I/O memory space contains 64 addresses for CPU peripheral functions as Control Registers, SPI, and other I/O functions. The I/O Memory can be accessed directly, or as the Data Space locations following those of the Register File, 0x20 - 0x5F. In addition, the Atmel ATmega325/3250/645/6450 has Extended I/O space from 0x60 - 0xFF in SRAM where only the ST/STS/STD and LD/LDS/LDD instructions can be used.

7.3 ALU – Arithmetic Logic Unit

The high-performance AVR ALU operates in direct connection with all the 32 general purpose working registers. Within a single clock cycle, arithmetic operations between general purpose registers or between a register and an immediate are executed. The ALU operations are divided into three main categories – arithmetic, logical, and bit-functions. Some implementations of the architecture also provide a powerful multiplier supporting both signed/unsigned multiplication and fractional format. See the “Instruction Set” section for a detailed description.

Figure 11-1. Reset Logic

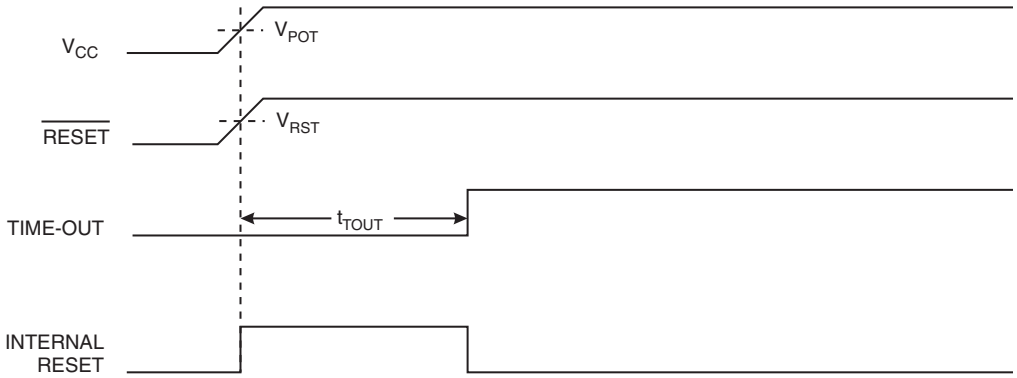


11.3 Power-on Reset

A Power-on Reset (POR) pulse is generated by an On-chip detection circuit. The detection level is defined in "System and Reset Characteristics" on page 301. The POR is activated whenever V_{CC} is below the detection level. The POR circuit can be used to trigger the start-up Reset, as well as to detect a failure in supply voltage.

A Power-on Reset (POR) circuit ensures that the device is reset from Power-on. Reaching the Power-on Reset threshold voltage invokes the delay counter, which determines how long the device is kept in RESET after V_{CC} rise. The RESET signal is activated again, without any delay, when V_{CC} decreases below the detection level.

Figure 11-2. MCU Start-up, $\overline{\text{RESET}}$ Tied to V_{CC}



corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it.

This bit is reserved bit in ATmega325/645 and will always be read as zero.

- **Bit 6– PCIF2: Pin Change Interrupt Flag 2**

When a logic change on any PCINT24..16 pin triggers an interrupt request, PCIF2 becomes set (one). If the I-bit in SREG and the PCIE2 bit in EIMSK are set (one), the MCU will jump to the corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it.

This bit is reserved bit in ATmega325/645 and will always be read as zero.

- **Bit 5– PCIF1: Pin Change Interrupt Flag 1**

When a logic change on any PCINT15..8 pin triggers an interrupt request, PCIF1 becomes set (one). If the I-bit in SREG and the PCIE1 bit in EIMSK are set (one), the MCU will jump to the corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it.

- **Bit 4– PCIF0: Pin Change Interrupt Flag 0**

When a logic change on any PCINT7..0 pin triggers an interrupt request, PCIF0 becomes set (one). If the I-bit in SREG and the PCIE0 bit in EIMSK are set (one), the MCU will jump to the corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it.

- **Bit 0 – INTF0: External Interrupt Flag 0**

When an edge or logic change on the INT0 pin triggers an interrupt request, INTF0 becomes set (one). If the I-bit in SREG and the INT0 bit in EIMSK are set (one), the MCU will jump to the corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it. This flag is always cleared when INT0 is configured as a level interrupt.

13.2.4 PCMSK3 – Pin Change Mask Register 3[(1)]

Bit	7	6	5	4	3	2	1	0	
(0x73)	–	PCINT30	PCINT29	PCINT28	PCINT27	PCINT26	PCINT25	PCINT24	PCMSK3
Read/Write	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 6:0 – PCINT30:24: Pin Change Enable Mask 30:24**

Each PCINT30:24-bit selects whether pin change interrupt is enabled on the corresponding I/O pin. If PCINT30:24 is set and the PCIE3 bit in EIMSK is set, pin change interrupt is enabled on the corresponding I/O pin. If PCINT30:24 is cleared, pin change interrupt on the corresponding I/O pin is disabled.

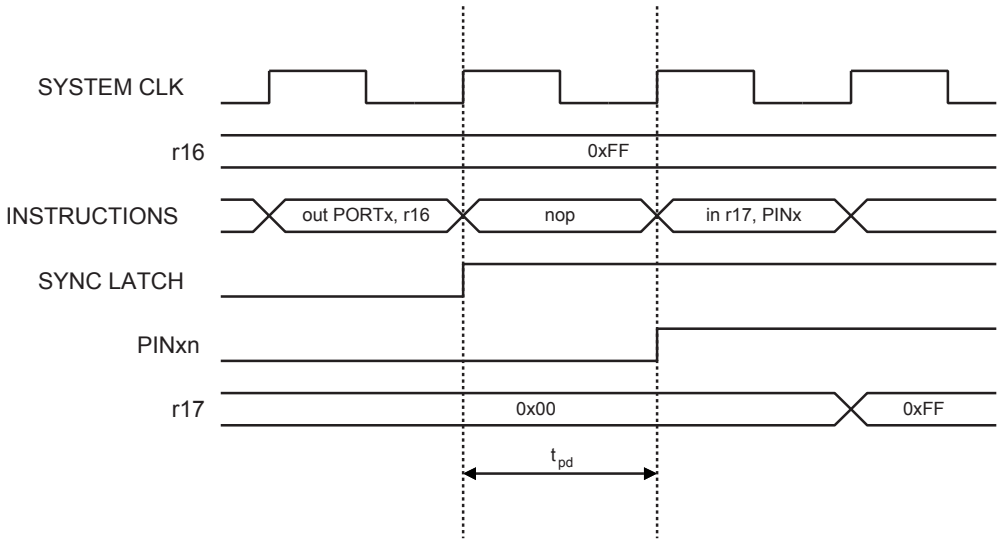
13.2.5 PCMSK2 – Pin Change Mask Register 2[(1)]

Bit	7	6	5	4	3	2	1	0	
(0x6D)	PCINT23	PCINT22	PCINT21	PCINT20	PCINT19	PCINT18	PCINT17	PCINT16	PCMSK2
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

Consider the clock period starting shortly after the first falling edge of the system clock. The latch is closed when the clock is low, and goes transparent when the clock is high, as indicated by the shaded region of the “SYNC LATCH” signal. The signal value is latched when the system clock goes low. It is clocked into the PINxn Register at the succeeding positive clock edge. As indicated by the two arrows tpd,max and tpd,min, a single signal transition on the pin will be delayed between ½ and 1½ system clock period depending upon the time of assertion.

When reading back a software assigned pin value, a nop instruction must be inserted as indicated in Figure 14-4. The out instruction sets the “SYNC LATCH” signal at the positive edge of the clock. In this case, the delay tpd through the synchronizer is 1 system clock period.

Figure 14-4. Synchronization when Reading a Software Assigned Pin Value



The following code example shows how to set port B pins 0 and 1 high, 2 and 3 low, and define the port pins from 4 to 7 as input with pull-ups assigned to port pins 6 and 7. The resulting pin values are read back again, but as previously discussed, a nop instruction is included to be able to read back the value recently assigned to some of the pins.

- **PCINT20 – Port H, Bit 4**

PCINT20, Pin Change Interrupt Source 20: The PH4 pin can serve as an external interrupt source.

- **PCINT19 – Port H, Bit 3**

PCINT19, Pin Change Interrupt Source 19: The PH3 pin can serve as an external interrupt source.

- **PCINT18 – Port H, Bit 2**

PCINT18, Pin Change Interrupt Source 18: The PH2 pin can serve as an external interrupt source.

- **PCINT17 – Port H, Bit 1**

PCINT17, Pin Change Interrupt Source 17: The P1 pin can serve as an external interrupt source.

- **PCINT16 – Port H, Bit 0**

PCINT16, Pin Change Interrupt Source 16: The PH0 pin can serve as an external interrupt source.

Table 14-17 and Table 14-18 relates the alternate functions of Port H to the overriding signals shown in Figure 14-5 on page 66.

Table 14-17. Overriding Signals for Alternate Functions in PH7:4

Signal Name	PH7/PCINT23	PH6/PCINT22	PH5/PCINT21	PH4/PCINT20
PUOE	0	0	0	0
PUOV	0	0	0	0
DDOE	0	0	0	0
DDOV	0	0	0	0
PVOE	0	0	0	0
PVOV	0	0	0	0
PTOE	–	–	–	–
DIEOE	PCINT23 • PCIE0	PCINT22 • PCIE0	PCINT21 • PCIE0	PCINT20 • PCIE0
DIEOV	0	0	0	0
DI	PCINT23 INPUT	PCINT22 INPUT	PCINT21 INPUT	PCINT20 INPUT
AIO	–	–	–	–

Figure 17-11. Timer/Counter Timing Diagram, Setting of OCF1x, with Prescaler ($f_{clk\_I/O}/8$)

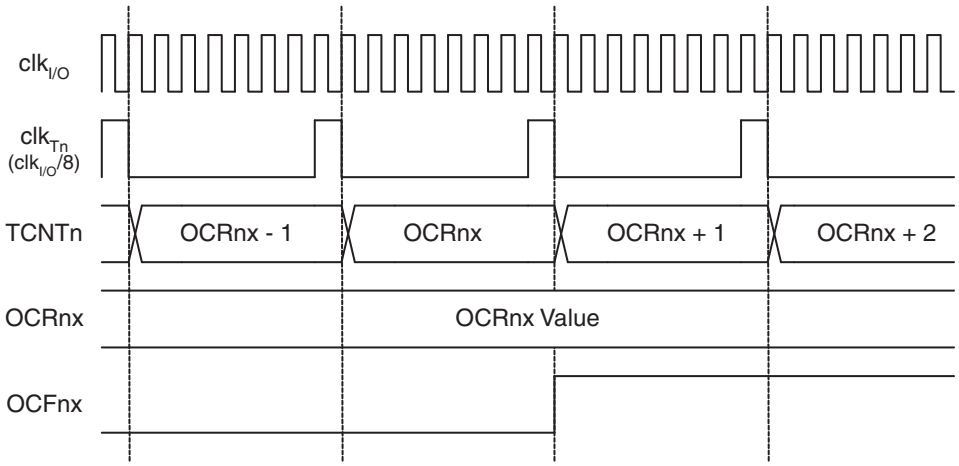


Figure 17-12 shows the count sequence close to TOP in various modes. When using phase and frequency correct PWM mode the OCR1x Register is updated at BOTTOM. The timing diagrams will be the same, but TOP should be replaced by BOTTOM, TOP-1 by BOTTOM+1 and so on. The same renaming applies for modes that set the TOV1 Flag at BOTTOM.

Figure 17-12. Timer/Counter Timing Diagram, no Prescaling

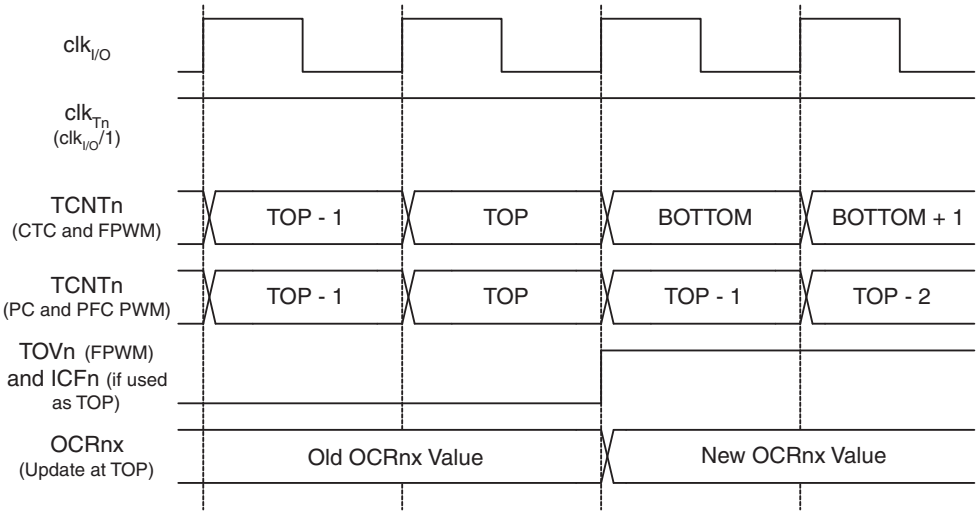


Figure 17-13 shows the same timing data, but with the prescaler enabled.

20.10 Examples of Baud Rate Setting

For standard crystal and resonator frequencies, the most commonly used baud rates for asynchronous operation can be generated by using the UBRR settings in Table 20-4. UBRR values which yield an actual baud rate differing less than 0.5% from the target baud rate, are bold in the table. Higher error ratings are acceptable, but the Receiver will have less noise resistance when the error ratings are high, especially for large serial frames (see "Asynchronous Operational Range" on page 173). The error values are calculated using the following equation:

$$\text{Error}[\%] = \left(\frac{\text{BaudRate}_{\text{Closest Match}}}{\text{BaudRate}} - 1\right) \bullet 100\%$$

Table 20-4. Examples of UBRR Settings for Commonly Used Oscillator Frequencies

Baud Rate (bps)	f_{osc} = 1.0000 MHz				f_{osc} = 1.8432 MHz				f_{osc} = 2.0000 MHz			
	U2Xn = 0		U2Xn = 1		U2Xn = 0		U2Xn = 1		U2Xn = 0		U2Xn = 1	
	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error
2400	**25**	**0.2%**	**51**	**0.2%**	**47**	**0.0%**	**95**	**0.0%**	**51**	**0.2%**	**103**	**0.2%**
4800	**12**	**0.2%**	**25**	**0.2%**	**23**	**0.0%**	**47**	**0.0%**	**25**	**0.2%**	**51**	**0.2%**
9600	6	-7.0%	**12**	**0.2%**	**11**	**0.0%**	**23**	**0.0%**	**12**	**0.2%**	**25**	**0.2%**
14.4k	3	8.5%	8	-3.5%	**7**	**0.0%**	**15**	**0.0%**	8	-3.5%	16	2.1%
19.2k	2	8.5%	6	-7.0%	**5**	**0.0%**	**11**	**0.0%**	6	-7.0%	**12**	**0.2%**
28.8k	1	8.5%	3	8.5%	**3**	**0.0%**	**7**	**0.0%**	3	8.5%	8	-3.5%
38.4k	1	-18.6%	2	8.5%	**2**	**0.0%**	**5**	**0.0%**	2	8.5%	6	-7.0%
57.6k	0	8.5%	1	8.5%	**1**	**0.0%**	**3**	**0.0%**	1	8.5%	3	8.5%
76.8k	–	–	1	-18.6%	1	-25.0%	**2**	**0.0%**	1	-18.6%	2	8.5%
115.2k	–	–	0	8.5%	**0**	**0.0%**	**1**	**0.0%**	0	8.5%	1	8.5%
230.4k	–	–	–	–	–	–	**0**	**0.0%**	–	–	–	–
250k	–	–	–	–	–	–	–	–	–	–	0	0.0%
Max. (1)	62.5 kbps		125 kbps		115.2 kbps		230.4 kbps		125 kbps		250 kbps	

1. UBRR = 0, Error = 0.0%

- **Bit 7 – ACD: Analog Comparator Disable**

When this bit is written logic one, the power to the Analog Comparator is switched off. This bit can be set at any time to turn off the Analog Comparator. This will reduce power consumption in Active and Idle mode. When changing the ACD bit, the Analog Comparator Interrupt must be disabled by clearing the ACIE bit in ACSR. Otherwise an interrupt can occur when the bit is changed.

- **Bit 6 – ACBG: Analog Comparator Bandgap Select**

When this bit is set, a fixed bandgap reference voltage replaces the positive input to the Analog Comparator. When this bit is cleared, AIN0 is applied to the positive input of the Analog Comparator. When the bandgap reference is used as input to the analog comparator, it will take a certain time for the voltage to stabilize. If not stabilized, the the first converison may give a wrong value. See “Internal Voltage Reference” on page 44.

- **Bit 5 – ACO: Analog Comparator Output**

The output of the Analog Comparator is synchronized and then directly connected to ACO. The synchronization introduces a delay of 1 - 2 clock cycles.

- **Bit 4 – ACI: Analog Comparator Interrupt Flag**

This bit is set by hardware when a comparator output event triggers the interrupt mode defined by ACIS1 and ACIS0. The Analog Comparator interrupt routine is executed if the ACIE bit is set and the I-bit in SREG is set. ACI is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, ACI is cleared by writing a logic one to the flag.

- **Bit 3 – ACIE: Analog Comparator Interrupt Enable**

When the ACIE bit is written logic one and the I-bit in the Status Register is set, the Analog Comparator interrupt is activated. When written logic zero, the interrupt is disabled.

- **Bit 2 – ACIC: Analog Comparator Input Capture Enable**

When written logic one, this bit enables the Input Capture function in Timer/Counter1 to be triggered by the Analog Comparator. The comparator output is in this case directly connected to the Input Capture front-end logic, making the comparator utilize the noise canceler and edge select features of the Timer/Counter1 Input Capture interrupt. When written logic zero, no connection between the Analog Comparator and the Input Capture function exists. To make the comparator trigger the Timer/Counter1 Input Capture interrupt, the ICIE1 bit in the Timer Interrupt Mask Register (TIMSK1) must be set.

with Auto triggering from a source other than the ADC Conversion Complete, each conversion will require 25 ADC clocks. This is because the ADC must be disabled and re-enabled after every conversion.

In Free Running mode, a new conversion will be started immediately after the conversion completes, while ADSC remains high. For a summary of conversion times, see Table 23-1.

Figure 23-4. ADC Timing Diagram, First Conversion (Single Conversion Mode)

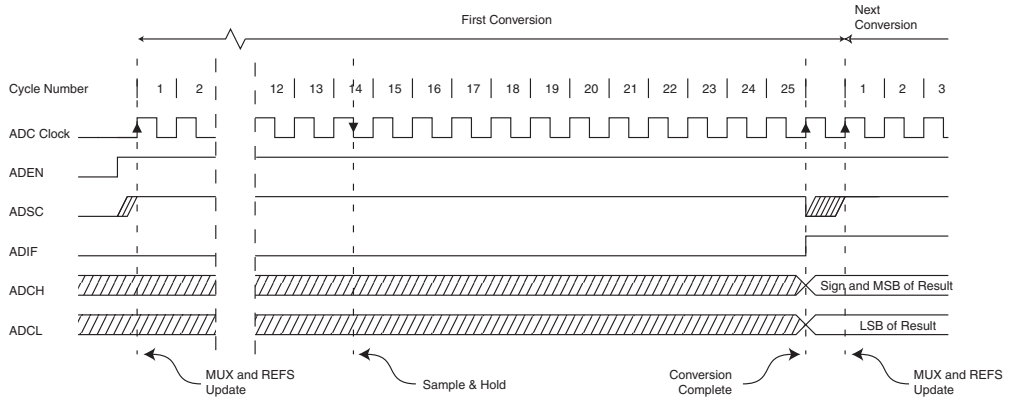


Figure 23-5. ADC Timing Diagram, Single Conversion

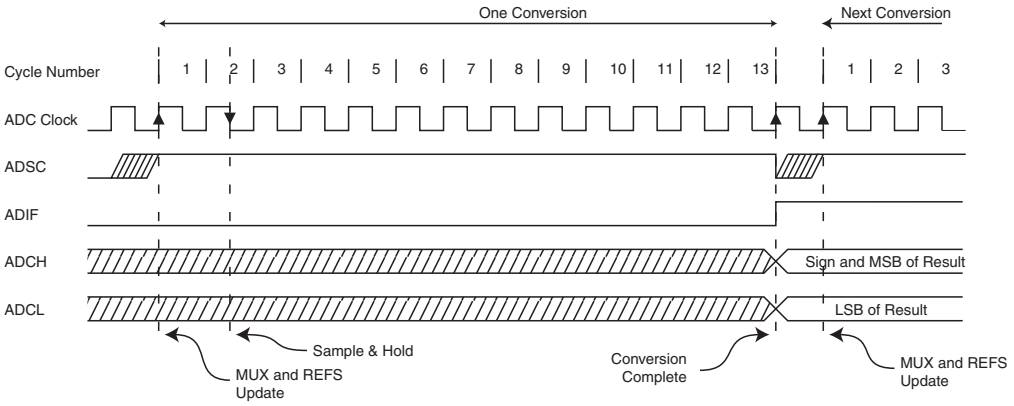
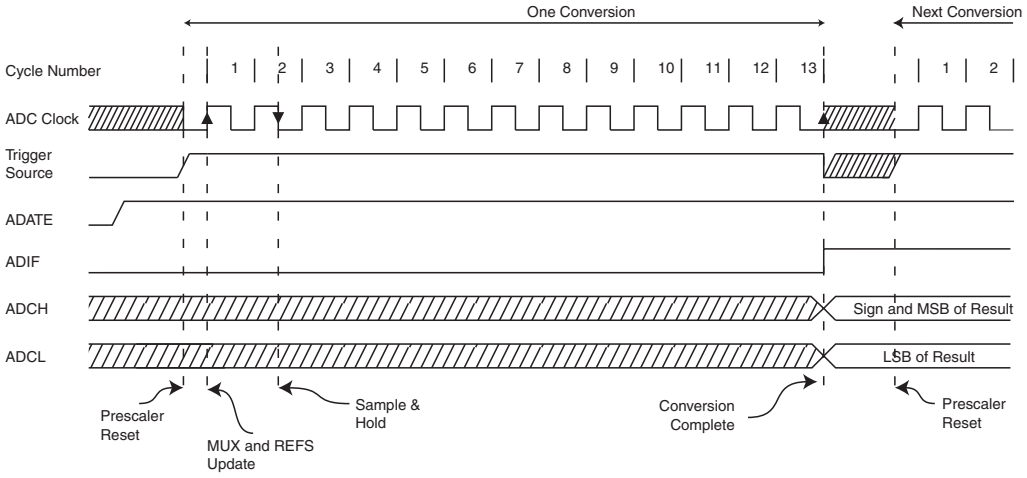


Figure 23-6. ADC Timing Diagram, Auto Triggered Conversion



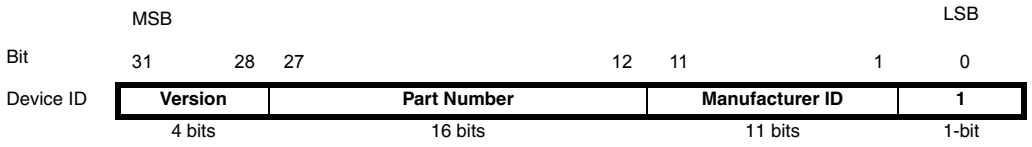
25.3.1 Bypass Register

The Bypass Register consists of a single Shift Register stage. When the Bypass Register is selected as path between TDI and TDO, the register is reset to 0 when leaving the Capture-DR controller state. The Bypass Register can be used to shorten the scan chain on a system when the other devices are to be tested.

25.3.2 Device Identification Register

Figure 25-1 shows the structure of the Device Identification Register.

Figure 25-1. The Format of the Device Identification Register



25.3.2.1 Version

Version is a 4-bit number identifying the revision of the component. The JTAG version number follows the revision of the device. Revision A is 0x0, revision B is 0x1 and so on.

25.3.2.2 Part Number

The part number is a 16-bit code identifying the component. The JTAG Part Number for Atmel ATmega325/3250/645/6450 is listed in Table 25-1.

Table 25-1. AVR JTAG Part Number

Part Number	JTAG Part Number (Hex)
ATmega325	0x9505
ATmega3250	0x9506
ATmega645	0x9605
ATmega6450	0x9606

25.3.2.3 Manufacturer ID

The Manufacturer ID is a 11-bit code identifying the manufacturer. The JTAG manufacturer ID for ATMEL is listed in Table 25-2.

Table 25-2. Manufacturer ID

Manufacturer	JTAG Manufacturer ID (Hex)
ATMEL	0x01F

25.3.3 Reset Register

The Reset Register is a test Data Register used to reset the part. Since the AVR tri-states Port Pins when reset, the Reset Register can also replace the function of the unimplemented optional JTAG instruction HIGHZ.

A high value in the Reset Register corresponds to pulling the external Reset low. The part is reset as long as there is a high value present in the Reset Register. Depending on the fuse settings for the clock options, the part will remain reset for a reset time-out period (refer to “Clock

Table 25-7. ATmega325/645 Boundary-scan Order, 64-pin (Continued)

Bit Number	Signal Name	Module
157	PE0.Data	Port E
156	PE0.Control	
155	PE0.Pull-up_Enable	
154	PE1.Data	
153	PE1.Control	
152	PE1.Pull-up_Enable	
151	PE2.Data	
150	PE2.Control	
149	PE2.Pull-up_Enable	
148	PE3.Data	
147	PE3.Control	
146	PE3.Pull-up_Enable	
145	PE4.Data	
144	PE4.Control	
143	PE4.Pull-up_Enable	
142	PE5.Data	
141	PE5.Control	
140	PE5.Pull-up_Enable	
139	PE6.Data	
138	PE6.Control	
137	PE6.Pull-up_Enable	
136	PE7.Data	
135	PE7.Control	
134	PE7.Pull-up_Enable	

26.4 Read-While-Write and No Read-While-Write Flash Sections

Whether the CPU supports Read-While-Write or if the CPU is halted during a Boot Loader software update is dependent on which address that is being programmed. In addition to the two sections that are configurable by the BOOTSZ Fuses as described above, the Flash is also divided into two fixed sections, the Read-While-Write (RWW) section and the No Read-While-Write (NRWW) section. The limit between the RWW- and NRWW sections is given in Table 26-7 on page 262 and Figure 26-2 on page 254. The main difference between the two sections is:

- When erasing or writing a page located inside the RWW section, the NRWW section can be read during the operation.
- When erasing or writing a page located inside the NRWW section, the CPU is halted during the entire operation.

Note that the user software can never read any code that is located inside the RWW section during a Boot Loader software operation. The syntax “Read-While-Write section” refers to which section that is being programmed (erased or written), not which section that actually is being read during a Boot Loader software update.

26.4.1 RWW – Read-While-Write Section

If a Boot Loader software update is programming a page inside the RWW section, it is possible to read code from the Flash, but only code that is located in the NRWW section. During an ongoing programming, the software must ensure that the RWW section never is being read. If the user software is trying to read code that is located inside the RWW section (i.e., by a call/jmp/lpm or an interrupt) during programming, the software might end up in an unknown state. To avoid this, the interrupts should either be disabled or moved to the Boot Loader section. The Boot Loader section is always located in the NRWW section. The RWW Section Busy bit (RWWSB) in the Store Program Memory Control and Status Register (SPMCSR) will be read as logical one as long as the RWW section is blocked for reading. After a programming is completed, the RWWSB must be cleared by software before reading code located in the RWW section. See “Store Program Memory Control and Status Register – SPMCSR” on page 263. for details on how to clear RWWSB.

26.4.2 NRWW – No Read-While-Write Section

The code located in the NRWW section can be read when the Boot Loader software is updating a page in the RWW section. When the Boot Loader code updates the NRWW section, the CPU is halted during the entire Page Erase or Page Write operation.

Table 26-1. Read-While-Write Features

Which Section does the Z-pointer Address During the Programming?	Which Section Can be Read During Programming?	Is the CPU Halted?	Read-While-Write Supported?
RWW Section	NRWW Section	No	Yes
NRWW Section	None	Yes	No

1. If there is no need for a Boot Loader update in the system, program the Boot Loader Lock bits to prevent any Boot Loader software updates.
2. Keep the AVR RESET active (low) during periods of insufficient power supply voltage. This can be done by enabling the internal Brown-out Detector (BOD) if the operating voltage matches the detection level. If not, an external low V_{CC} reset protection circuit can be used. If a reset occurs while a write operation is in progress, the write operation will be completed provided that the power supply voltage is sufficient.
3. Keep the AVR core in Power-down sleep mode during periods of low V_{CC}. This will prevent the CPU from attempting to decode and execute instructions, effectively protecting the SPMCSR Register and thus the Flash from unintentional writes.

26.8.11 Programming Time for Flash when Using SPM

The calibrated RC Oscillator is used to time Flash accesses. Table 26-5 shows the typical programming time for Flash accesses from the CPU.

Table 26-5. SPM Programming Time

Symbol	Min Programming Time	Max Programming Time
Flash write (Page Erase, Page Write, and write Lock bits by SPM)	3.7ms	4.5ms

26.8.12 Simple Assembly Code Example for a Boot Loader

```
  ;-the routine writes one page of data from RAM to Flash
  ; the first data location in RAM is pointed to by the Y pointer
  ; the first data location in Flash is pointed to by the Z-pointer
  ;-error handling is not included
  ;-the routine must be placed inside the Boot space
  ; (at least the Do_spm sub routine). Only code inside NRWW section can
  ; be read during Self-Programming (Page Erase and Page Write).
  ;-registers used: r0, r1, temp1 (r16), temp2 (r17), looplo (r24),
  ; loophi (r25), spmcrval (r20)
  ; storing and restoring of registers is not included in the routine
  ; register usage can be optimized at the expense of code size
  ;-It is assumed that either the interrupt table is moved to the Boot
  ; loader section or that the interrupts are disabled.
.equ PAGESIZEB = PAGESIZE*2   ;PAGESIZEB is page size in BYTES, not words
.org SMALLBOOTSTART
Write_page:
  ; Page Erase
  ldi  spmcrval, (1<<PGERS) | (1<<SPMEN)
  call Do_spm

  ; re-enable the RWW section
  ldi  spmcrval, (1<<RWWSRE) | (1<<SPMEN)
  call Do_spm

  ; transfer data from RAM to Flash page buffer
  ldi  looplo, low(PAGESIZEB)   ;init loop variable
  ldi  loophi, high(PAGESIZEB)  ;not required for PAGESIZEB<=256
Wrloop:
  ld   r0, Y+
  ld   r1, Y+
  ldi  spmcrval, (1<<SPMEN)
  call Do_spm
  adiw ZH:ZL, 2
  sbiw loophi:looplo, 2         ;use subi for PAGESIZEB<=256
```

The status of the Fuse bits is not affected by Chip Erase. Note that the Fuse bits are locked if Lock bit1 (LB1) is programmed. Program the Fuse bits before programming the Lock bits.

27.2.1 Latching of Fuses

The fuse values are latched when the device enters programming mode and changes of the fuse values will have no effect until the part leaves Programming mode. This does not apply to the EESAVE Fuse which will take effect once it is programmed. The fuses are also latched on Power-up in Normal mode.

27.3 Signature Bytes

All Atmel microcontrollers have a three-byte signature code which identifies the device. This code can be read in both serial and parallel mode, also when the device is locked. The three bytes reside in a separate address space.

For the Atmel ATmega325/3250/645/6450 the signature bytes are:

1. 0x000: 0x1E (indicates manufactured by Atmel).
2. 0x001: 0x95/0x96 (indicates Flash memory, refer to “Part Number” on page 225).
3. 0x002: 0x05/0x06 (indicates device, refer to “Part Number” on page 225).

27.4 Calibration Byte

The Atmel ATmega325/3250/645/6450 has a byte calibration value for the internal RC Oscillator. This byte resides in the high byte of address 0x000 in the signature address space. During reset, this byte is automatically written into the OSCCAL Register to ensure correct frequency of the calibrated RC Oscillator.

27.5 Parallel Programming Parameters, Pin Mapping, and Commands

This section describes how to parallel program and verify Flash Program memory, EEPROM Data memory, Memory Lock bits, and Fuse bits in the Atmel ATmega325/3250/645/6450. Pulses are assumed to be at least 250ns unless otherwise noted.

27.5.1 Signal Names

In this section, some pins of the Atmel ATmega325/3250/645/6450 are referenced by signal names describing their functionality during parallel programming, see Figure 27-1 and Table 27-6. Pins not described in the following table are referenced by pin names.

The XA1/XA0 pins determine the action executed when the XTAL1 pin is given a positive pulse. The bit coding is shown in Table 27-8.

When pulsing $\overline{WR}$ or $\overline{OE}$, the command loaded determines the action executed. The different Commands are shown in Table 27-9.

1. Set XA1, XA0 to “10”. This enables command loading.
2. Set BS1 to “0”.
3. Set DATA to “1000 0000”. This is the command for Chip Erase.
4. Give XTAL1 a positive pulse. This loads the command.
5. Give $\overline{WR}$ a negative pulse. This starts the Chip Erase. RDY/$\overline{BSY}$ goes low.
6. Wait until RDY/$\overline{BSY}$ goes high before loading a new command.

27.6.4 Programming the Flash

The Flash is organized in pages, see Table 27-10 on page 270. When programming the Flash, the program data is latched into a page buffer. This allows one page of program data to be programmed simultaneously. The following procedure describes how to program the entire Flash memory:

A. Load Command “Write Flash”

1. Set XA1, XA0 to “10”. This enables command loading.
2. Set BS1 to “0”.
3. Set DATA to “0001 0000”. This is the command for Write Flash.
4. Give XTAL1 a positive pulse. This loads the command.

B. Load Address Low byte

1. Set XA1, XA0 to “00”. This enables address loading.
2. Set BS1 to “0”. This selects low address.
3. Set DATA = Address low byte (0x00 - 0xFF).
4. Give XTAL1 a positive pulse. This loads the address low byte.

C. Load Data Low Byte

1. Set XA1, XA0 to “01”. This enables data loading.
2. Set DATA = Data low byte (0x00 - 0xFF).
3. Give XTAL1 a positive pulse. This loads the data byte.

D. Load Data High Byte

1. Set BS1 to “1”. This selects high data byte.
2. Set XA1, XA0 to “01”. This enables data loading.
3. Set DATA = Data high byte (0x00 - 0xFF).
4. Give XTAL1 a positive pulse. This loads the data byte.

E. Latch Data

1. Set BS1 to “1”. This selects high data byte.
2. Give PAGEL a positive pulse. This latches the data bytes. (See Figure 27-3 for signal waveforms)

F. Repeat B through E until the entire buffer is filled or until all data within the page is loaded.

While the lower bits in the address are mapped to words within the page, the higher bits address the pages within the FLASH. This is illustrated in Figure 27-2 on page 273. Note that if less than eight bits are required to address words in the page (pagesize < 256), the most significant bit(s) in the address low byte are used to address the page when performing a Page Write.

G. Load Address High byte

28. Electrical Characteristics

28.1 Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on any Pin except $\overline{\text{RESET}}$ with respect to Ground	-0.5V to V_{CC}+0.5V
Voltage on $\overline{\text{RESET}}$ with respect to Ground	-0.5V to +13.0V
Maximum Operating Voltage	6.0V
DC Current per I/O Pin	40.0 mA
DC Current V_{CC} and GND Pins	200.0 mA

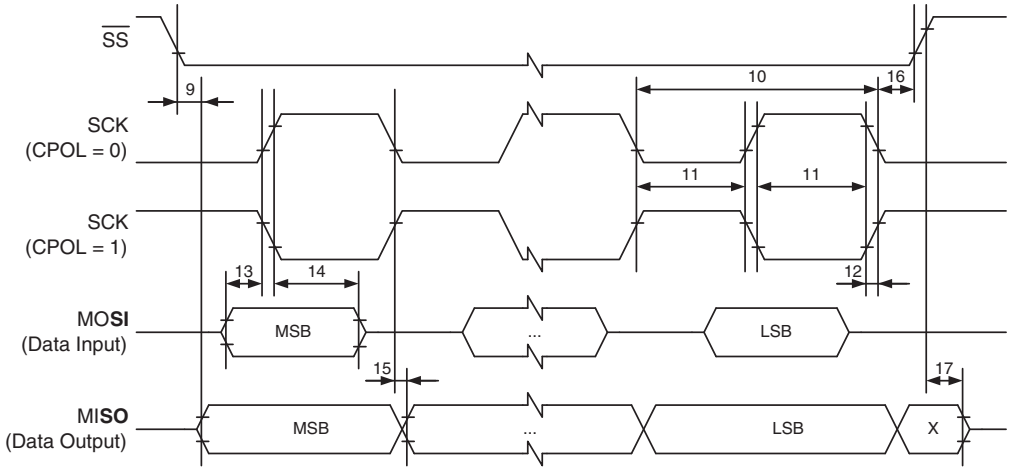
*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

28.2 DC Characteristics

Table 28-1. T_A = -40°C to 85°C, V_{CC} = 1.8V to 5.5V (unless otherwise noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{IL}	Input Low Voltage, Except XTAL1 pin	V_{CC} = 1.8V - 2.4V V_{CC} = 2.4V - 5.5V	-0.5 -0.5		$0.2V_{CC}$ (1) $0.3V_{CC}$ (1)	V
V_{IL1}	Input Low Voltage, XTAL1 pin	V_{CC} = 1.8V - 5.5V	-0.5		$0.1V_{CC}$ (1)	V
V_{IH}	Input High Voltage, Except XTAL1 and RESET pins	V_{CC} = 1.8V - 2.4V V_{CC} = 2.4V - 5.5V	$0.7V_{CC}$ (2) $0.6V_{CC}$ (2)		V_{CC} + 0.5 V_{CC} + 0.5	V
V_{IH1}	Input High Voltage, XTAL1 pin	V_{CC} = 1.8V - 2.4V V_{CC} = 2.4V - 5.5V	$0.8V_{CC}$ (2) $0.7V_{CC}$ (2)		V_{CC} + 0.5 V_{CC} + 0.5	V
V_{IH2}	Input High Voltage, RESET pin	V_{CC} = 1.8V - 5.5V	$0.85V_{CC}$ (2)		V_{CC} + 0.5	V
V_{OL}	Output Low Voltage (3), Port A, C, D, E, F, G, H, J	I_{OL} = 10mA, V_{CC} = 5V I_{OL} = 5mA, V_{CC} = 3V			0.7 0.5	V
V_{OL1}	Output Low Voltage (3), Port B	I_{OL} = 20mA, V_{CC} = 5V I_{OL} = 10mA, V_{CC} = 3V			0.7 0.5	V
V_{OH}	Output High Voltage (4), Port A, C, D, E, F, G, H, J	I_{OH} = -10mA, V_{CC} = 5V I_{OH} = -5mA, V_{CC} = 3V	4.2 2.3			V
V_{OH1}	Output High Voltage (4), Port B	I_{OH} = -20mA, V_{CC} = 5V I_{OH} = -10mA, V_{CC} = 3V	4.2 2.3			V
I_{IL}	Input Leakage Current I/O Pin	V_{CC} = 5.5V, pin low (absolute value)			1	µA
I_{IH}	Input Leakage Current I/O Pin	V_{CC} = 5.5V, pin high (absolute value)			1	µA
R_{RST}	Reset Pull-up Resistor		20		100	kΩ
R_{PU}	I/O Pin Pull-up Resistor		20		100	kΩ

Figure 28-5. SPI Interface Timing Requirements (Slave Mode)



29.12 Current Consumption of Peripheral Units

Figure 29-49. Brownout Detector Current vs. V_{CC}

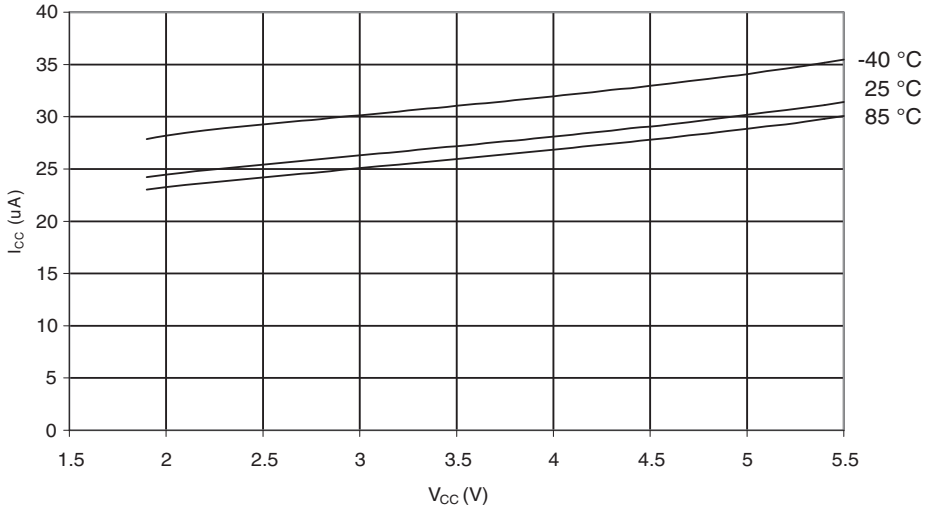
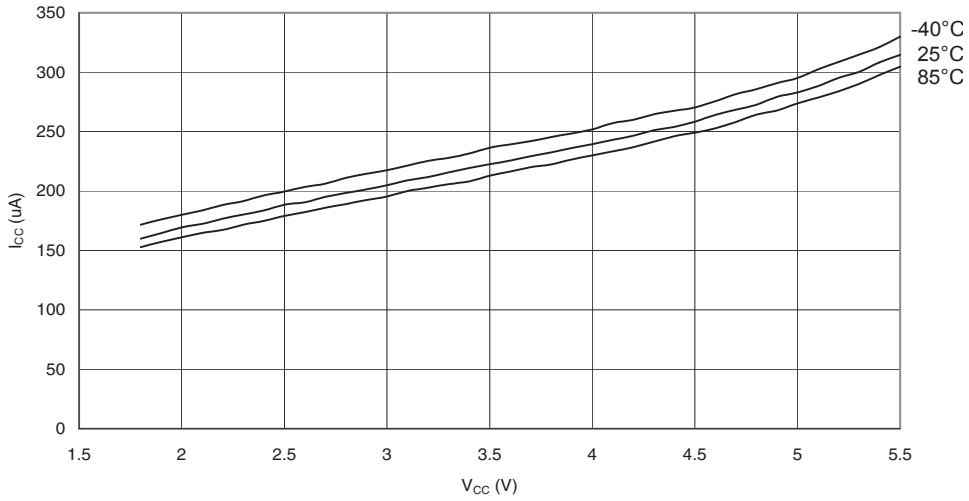


Figure 29-50. ADC Current vs. V_{CC} (AREF = AVCC)



34. Errata

34.1 Errata ATmega325

The revision letter in this section refers to the revision of the ATmega325 device.

34.1.1 ATmega325 Rev. C

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**
   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/ Workaround
   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

34.1.2 ATmega325 Rev. B

Not sampled.

34.1.3 ATmega325 Rev. A

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**
   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/ Workaround
   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

34.2 Errata ATmega3250

The revision letter in this section refers to the revision of the ATmega3250 device.

34.2.1 ATmega3250 Rev. C

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**
   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/ Workaround
   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

34.2.2 ATmega3250 Rev. B

Not sampled.

35. Datasheet Revision History

Please note that the referring page numbers in this section are referring to this document. The referring revision in this section are referring to the document revision.

35.1 Rev. 2570N – 05/11

1. Added Atmel QTouch Library Support and QTouch Sensing Capablity Features.
2. Updated the last page with Atmel® trademarks and Microsft Windows® trademarks.

35.2 Rev. 2570M – 04/11

1. Removed “Preliminary” from the front page
2. Removed “Disclaimer” section from the datasheet
3. Updated Table 28-5 on page 301 “BODLEVEL Fuse Coding(1)”
4. Updated “Ordering Information” on page 343 to include the “Tape & Reel” devices. Removed “AI” and “MI” devices.
5. Updated “Errata” on page 350.
6. Updated the datasheet according to the Atmel new drand style guide, including the last page.

35.3 Rev. 2570L – 08/07

1. Updated “Features” on page 1.
2. Added “Data Retention” on page 9
3. Updated “Serial Programming Algorithm” on page 281.
4. Updated “Speed Grades” on page 299.
5. Updated “System and Reset Characteristics” on page 301.
6. Updated the Register Description at the end of each chapter.

35.4 Rev. 2570K – 04/07

1. Updated “Errata” on page 350.

35.5 Rev. 2570J – 11/06

1. Updated Table 28-7 on page 304.
2. Updated note in Table 28-7 on page 304.